

# BF 1608 Series

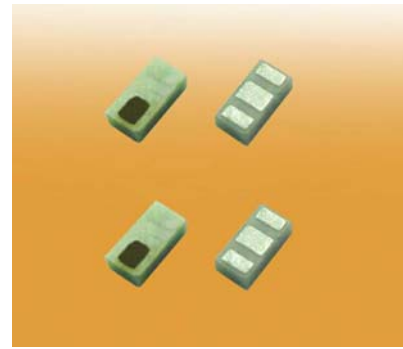
Multilayer Chip Band-Pass Filters

## Features

- ❖ Ultra small SMD type with low loss at pass-band and high attenuation at stop-band.
- ❖ RoHS compliant

## Applications

- ❖ WiFi communication systems.



## Specifications

Part Number	Frequency Range (MHz)	Insertion Loss @ BW (dB)	Return Loss @ BW (dB)	Frequency (MHz)	Attenuation (dB)
BF1608-N5R5NAH_	5150~5950	0.7 max.	12 min.	700 ~ 2690	35 min.
				3400 ~ 3800	30 min.
				7250 ~ 7800	12 min.
				10300 ~ 11700	20 min.
				15450 ~ 17850	4 typ.

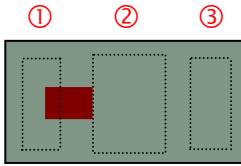
Q'ty/Reel (pcs) : 4,000  
 Operating Temperature Range : -40 ~ +85 °C  
 Storage Temperature Range : -40 ~ +85 °C  
 Storage Period : 12 months max.  
 Power Capacity : 3W max.

## Part Number

BF   1608   -   N   5R5   NAH   □   /LF  
 ①   ②   ③   ④   ⑤   ⑥   ⑦

① Type	BF : Band-Pass Filter	② Dimensions ( L x W )	1.6 x 0.8 mm
③ Material Code	N	④ Frequency Range	5R5=5500MHz
⑤ Specification Code	NAH	⑥ Packaging	T: Tape & Reel B: Bulk
⑦ Soldering	/LF=lead-free		

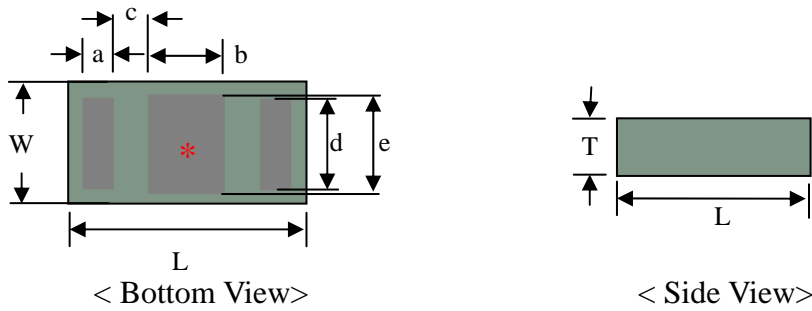
## Terminal Configuration



No.	Terminal Name	No.	Terminal Name
①	IN	③	OUT
②	GND		

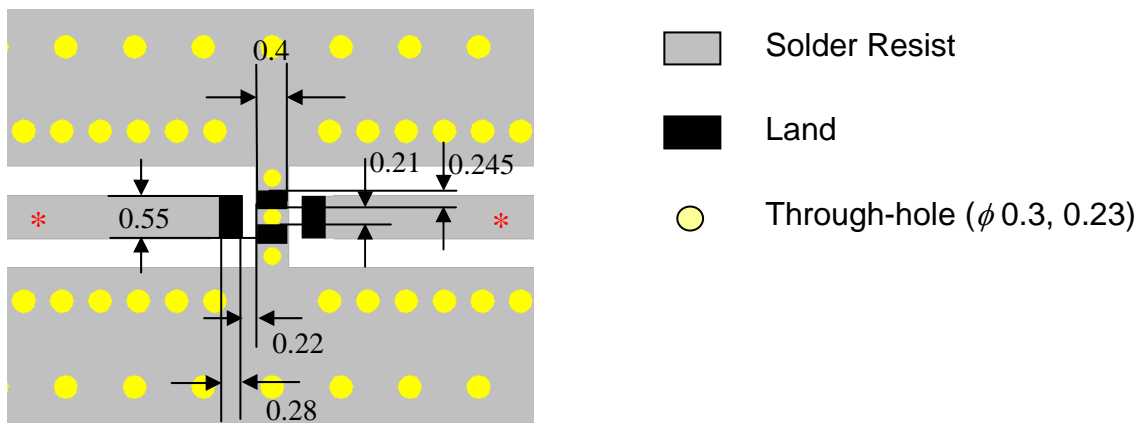
## Dimensions and Recommended PC Board Pattern

Unit: mm



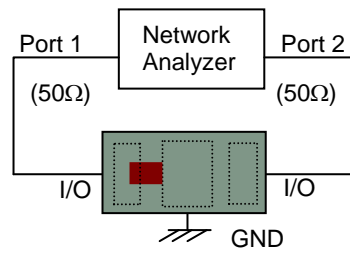
\*Electrode material: Ni/Sn

Mark	L	W	T	a	b	c	d	e
Dimensions	1.6 ±	0.8 ±	0.6	0.25 ±	0.4 ±	0.23 ±	0.55 ±	0.60 ±
	0.15	0.15	max.	0.1	0.1	0.05	0.10	0.10

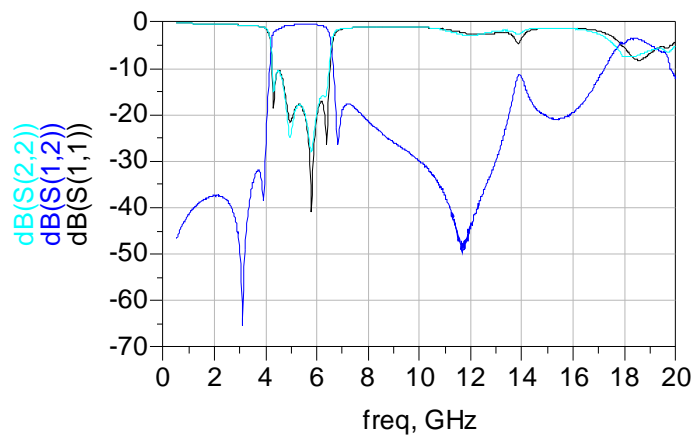


\* Line width should be designed to match 50  $\Omega$  characteristic impedance, depending on PCB material and thickness.

## Measuring Diagram



## Electrical Characteristics (T=25oC)

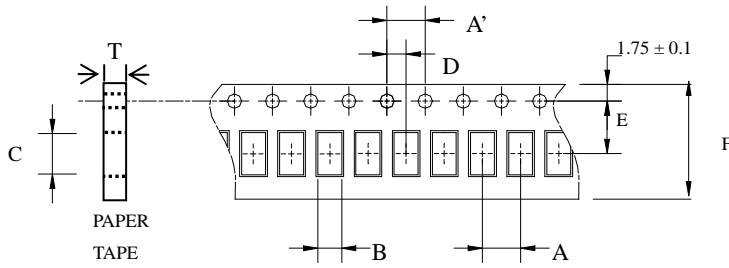


## Notes

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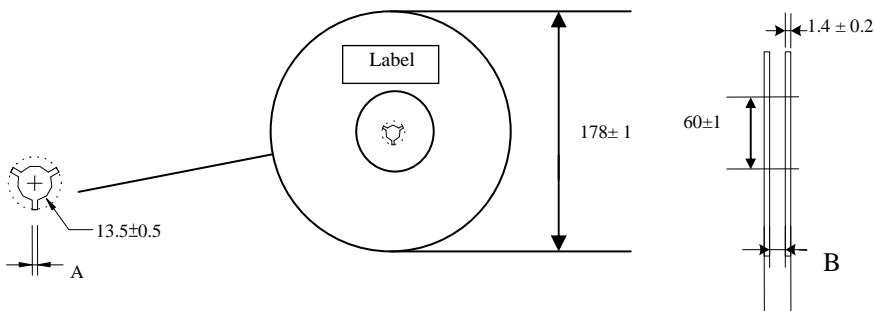
## Taping Specifications

### ❖Tape Dimensions (Unit: mm) & Quantity



Type	A	A'	B	C	D	E	F	T	Quantity/reel	Tape material
1608	4.0±	4.0±	1.10±	1.92±	2.0±	3.5±	8.0±	0.75±	4,000pcs	Paper
	0.1	0.1	0.1	0.1	0.1	0.1	0.1	0.05		

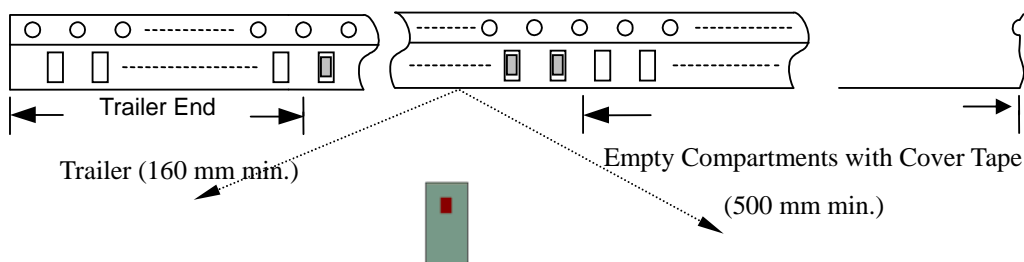
### ❖Reel Dimensions (Unit: mm)



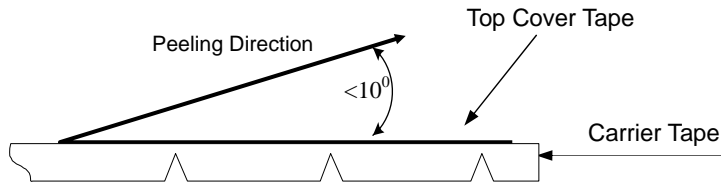
Label: Customer's Name,  
ACX P/N, Q'ty, Date,  
ACX Corp.

Type	A	B
1608	2.3±0.5	9.0±0.3

### ❖Leader and Trailer Tape



❖ **Peel-off Force**



Peel-off force should be in the range of 0.1 – 0.6 N at a peel-off speed of  $300 \pm 10$  mm/min .

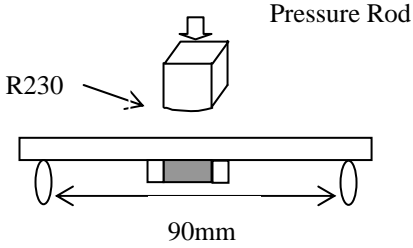
❖ **Storage Conditions**

- (1) Temperature: 5 ~35°C , relative humidity (RH): 45~75%.
- (2) Non-corrosive environment.

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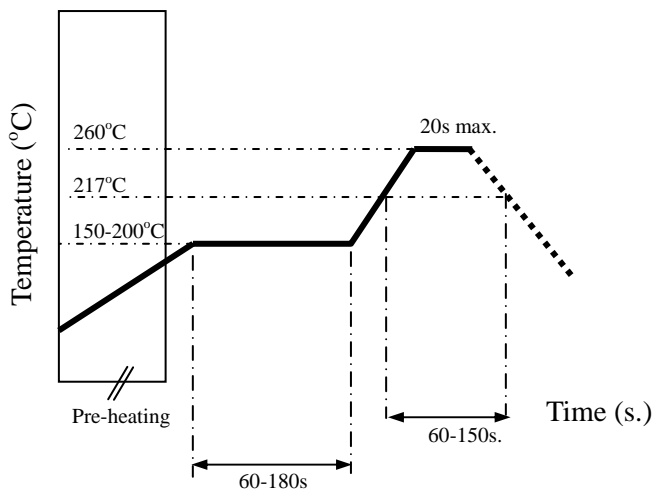
## Mechanical & Environmental Characteristics

Item	Requirements	Procedure
Solderability	<ol style="list-style-type: none"> <li>No apparent damage</li> <li>More than 95% of the terminal electrode shall be covered with new solder</li> </ol>	<ol style="list-style-type: none"> <li>Preheat: <math>120 \pm 5^\circ\text{C}</math></li> <li>Solder: <math>245 \pm 5^\circ\text{C}</math> for <math>5 \pm 1</math> sec</li> </ol>
Soldering strength (Termination Adhesion)	<ol style="list-style-type: none"> <li>1kg minimum</li> </ol>	<ol style="list-style-type: none"> <li>Solder specimen onto test jig.</li> <li>Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction</li> </ol>
Deflection (Substrate Bending)	<ol style="list-style-type: none"> <li>No apparent damage</li> </ol>	<ol style="list-style-type: none"> <li>Solder specimen onto test jig (FR4, 0.8mm) using the recommend soldering profile.</li> <li>Apply a bending force of 2mm deflection. (Chip length &lt; 4.5mm)</li> </ol> 
Heat/Humidity Resistance	<ol style="list-style-type: none"> <li>No apparent damage</li> <li>Fulfill the electrical specification after test</li> </ol>	<ol style="list-style-type: none"> <li>Temperature: <math>85 \pm 2^\circ\text{C}</math></li> <li>Humidity: 90% ~ 95% RH</li> <li>Duration: <math>1000 \pm 48</math> hrs</li> <li>Recovery: 1-2hrs</li> </ol>
Thermal shock (Temperature Cycle)	<ol style="list-style-type: none"> <li>No apparent damage</li> <li>Fulfill the electrical specification after test</li> </ol>	<ol style="list-style-type: none"> <li>One cycle/step 1 : <math>125 \pm 5^\circ\text{C}</math> for 30 min step 2 : <math>-40 \pm 5^\circ\text{C}</math> for 30 min</li> <li>No of cycles : 100</li> <li>Recovery: 1-2 hrs</li> </ol>
Low Temperature Resistance	<ol style="list-style-type: none"> <li>No apparent damage</li> <li>Fulfill the electrical specification after test</li> </ol>	<ol style="list-style-type: none"> <li>Temperature: <math>-40 \pm 5^\circ\text{C}</math></li> <li>Duration: <math>500 \pm 24</math> hrs</li> <li>Recovery: 1-2hrs</li> </ol>

## Soldering Conditions

### ❖ Typical Soldering Profile for Lead-free Process

Reflow Soldering :



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